

## AMENDMENTS TO THE CLAIMS

*Claims 1-82. (Canceled)*

*Claims 83-105. (Canceled)*

106. (New) An electrolytic processing apparatus comprising:

- a substrate holder for holding a substrate such that a surface, to be processed, of the substrate faces upwardly;
- a first electrode for being brought into contact with the substrate so as to supply current to the surface of the substrate;
- a second electrode disposed above said substrate holder such that when the substrate is held by said substrate holder said second electrode is substantially parallel to the surface of the substrate;
- a resistance structure between said substrate holder and said second electrode such that when the substrate is held by said substrate holder said resistance structure is between the substrate and said second electrode;
- an electrolytic solution introducing portion for introducing an electrolytic solution, from laterally of said resistance structure, into a region across which the substrate and said resistance structure face each other when the substrate is held by said substrate holder, so as to allow the electrolytic solution to flow along the surface of the substrate;
- a power source for applying a voltage between said first electrode and said second electrode; and
- another electrolytic solution introducing portion for introducing the electrolytic solution, from laterally of said resistance structure, into the region across which the substrate and said resistance structure face each other when the substrate is held by said substrate holder,

wherein said electrolytic solution introducing portion and said another electrolytic solution introducing portion are in positions facing one another other across the substrate when held by said substrate holder, and

wherein said resistance structure is a high resistance structure by virtue of being constituted to have lower electric conductivity than that of the electrolytic solution by causing the electrolytic solution to enter into said resistance structure.

107. (New) An electrolytic processing apparatus comprising:

a substrate holder for holding a substrate such that a surface, to be processed, of the substrate faces upwardly;

a first electrode for being brought into contact with the substrate so as to supply current to the surface of the substrate;

a second electrode disposed above said substrate holder such that when the substrate is held by said substrate holder said second electrode is substantially parallel to the surface of the substrate;

a resistance structure between said substrate holder and said second electrode such that when the substrate is held by said substrate holder said resistance structure is between the substrate and said second electrode;

an electrolytic solution introducing portion for introducing an electrolytic solution, from laterally of said resistance structure, into a region across which the substrate and said resistance structure face each other when the substrate is held by said substrate holder, so as to allow the electrolytic solution to flow along the surface of the substrate;

a power source for applying a voltage between said first electrode and said second electrode;

another electrolytic solution introducing portion for introducing the electrolytic solution, from laterally of said resistance structure, into the region across which the substrate and said resistance structure face each other when the substrate is held by said substrate holder;

a first liquid delivery pump, connected to said electrolytic solution introducing portion, for delivering the electrolytic solution from said electrolytic solution introducing portion at spaced time intervals; and

a second liquid delivery pump, connected to said another electrolytic solution introducing portion, for delivering the electrolytic solution from said another electrolytic solution introducing portion at spaced time intervals,

wherein said resistance structure is a high resistance structure by virtue of being constituted to have lower electric conductivity than that of the electrolytic solution by causing the electrolytic solution to enter into said resistance structure.